Revision: 1.0
Date: 7-Feb-05

Statement of Materials, Construction

LEAD-FREE -- 8L MSOP -- TABLE OF MATERIAL DECLARATION

No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.01010000	Cu	7440-50-8	0.00984	35.16951	97.43
				Fe	7439-89-6	0.00024	0.84828	2.35
				Pb	7439-92-1	0.00000	0.01083	0.03
				P	7723-14-0	0.00001	0.02996	0.083
				Zn	7440-66-6	0.00001	0.04693	0.13
2	Die	Silicon Chip	0.001000	Si	7440-21-3	0.00161	5.75768	99.95
3	Die attach material	Conductive Epoxy	0.0003800	Epoxy resin (5-25)	Proprietary	0.00006	0.20372	15
				Silver (70-85)	7440-21-3	0.00030	1.07970	79.5
				Aromatic Amine (1-10)	Proprietary	0.00002	0.07470	5.5
4	Wire	Gold	0.003100	Au	7440-57-5	0.00310	11.07823	99.99
5	Lead Finish	Tin	0.000700	Sn	7440-31-5	0.00070	2.50179	100
6	Encapsulation	Epoxy Resin	0.0127	Fused Silica	60676-86-0	0.01092	39.03503	86
				Epoxy Resin Type A	Proprietary	0.00076	2.72337	6
				Epoxy Resin Type B	Proprietary	0.00019	0.68084	1.5
				Phenol Novalac	9003-35-4	0.00051	1.81558	4
				Antimony trioxide	1309-64-4	0.00019	0.68084	1.5
				Brominated Epoxy Resin	68541-54-0	0.00008	0.27234	0.6
				Carbon Black	1333-86-4	0.00004	0.13617	0.3
Total Package weight			0.02798					

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

* Lead is allowed up to 4% as an alloying agent in copper-based alloys